WinWay

Your Trusted Partner in Semiconductor Testing

股票代號 6515

穎崴科技股份有限公司

法人說明會

2025.11.20

免責聲明

本簡報及同時發佈之相關訊息所提及之預測性資訊，包括營運展望、財務狀況及業務預測等內容，係本公司基於內部資料及外部整體經濟發展現況所得之資訊。

本公司未來實際所可能產生的營運結果、財務狀況與業務成果，可能與預測性資訊有所差異。其原因可能來自各種因素，包括但不限於市場需求、價格波動、競爭態勢、各種政策法令與金融經濟現況之改變，以及其他本公司無法掌控之風險等因素。

本簡報中所提供之資訊，係反應本公司截至目前為止對於未來的看法，並未明示或暗示性地表達或保證其具有正確性、完整性或可靠性。對於這些看法，未來若有變更或調整時，本公司並不負有更新或修正之責任。

公司簡介

成立日期

西元 2001 年 4 月 10 日

董事長兼總經理

王嘉煌

員工人數

1068人

服務項目

半導體測試介面研發設計及製造銷售

實收資本額

NTD 360,491,820

登記地址

高雄市楠梓區創意南路68號

美國分公司

高雄總公司

新竹分公司

經營理念

始終站在客戶的角度思考半導體測試需求，並透過客戶參與、技術創新、製造管理及供應鏈整合，持續堅持品質，服務全球，致力於為客戶、員工、供應商及股東創造最大的福利並善盡社會責任。

持續創新

透過技術創新
爲客戶打造最佳
測試介面解決方案

堅持品質

提供整體解決方案
並於全球準時交付
超越客戶的品質要求

全球服務

致力成爲全球領先的
專業測試服務供應商
在 IC 測試各階段提供最佳服務

簡報大綱

01
全球
布局

02
產業
趨勢

03
經營
績效

04
研發
創新

01 全球布局

WinWay
穎崴科技

技術創新 服務全球

高雄探針廠

Spring Probe
for Socket

高雄廠

Coaxial Socket
HyperSocket™

新竹廠

Vertical Probe Card
MEMS Probe Card

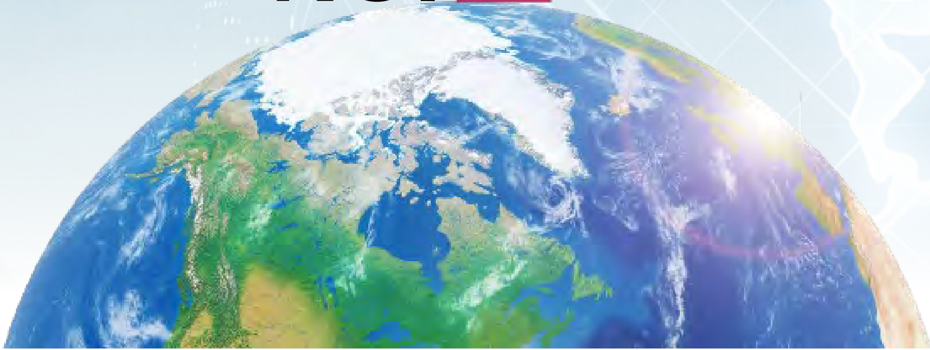
蘇州廠

Burn-in Socket

專注半導體測試介面技術

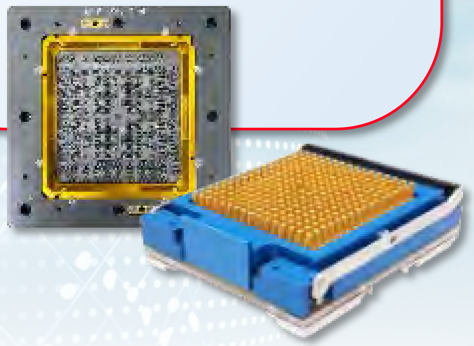
2024
Test Socket Ranking

NO.1



2024
Test and Burn-in Socket Ranking

NO.2



Source：Yole Intelligence, 2025/04

WinWay
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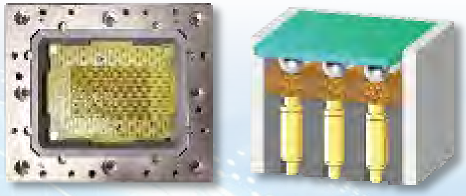
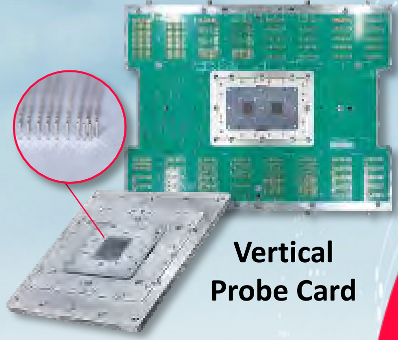
Your Trusted Partner in Semiconductor Testing


Plastic Socket & RF Socket


Coaxial Socket & HyperSocket™


Vertical Probe Card

晶圓測試
Wafer Sort

最終測試
Final Test

高頻高速
系統測試
SLT & SFT

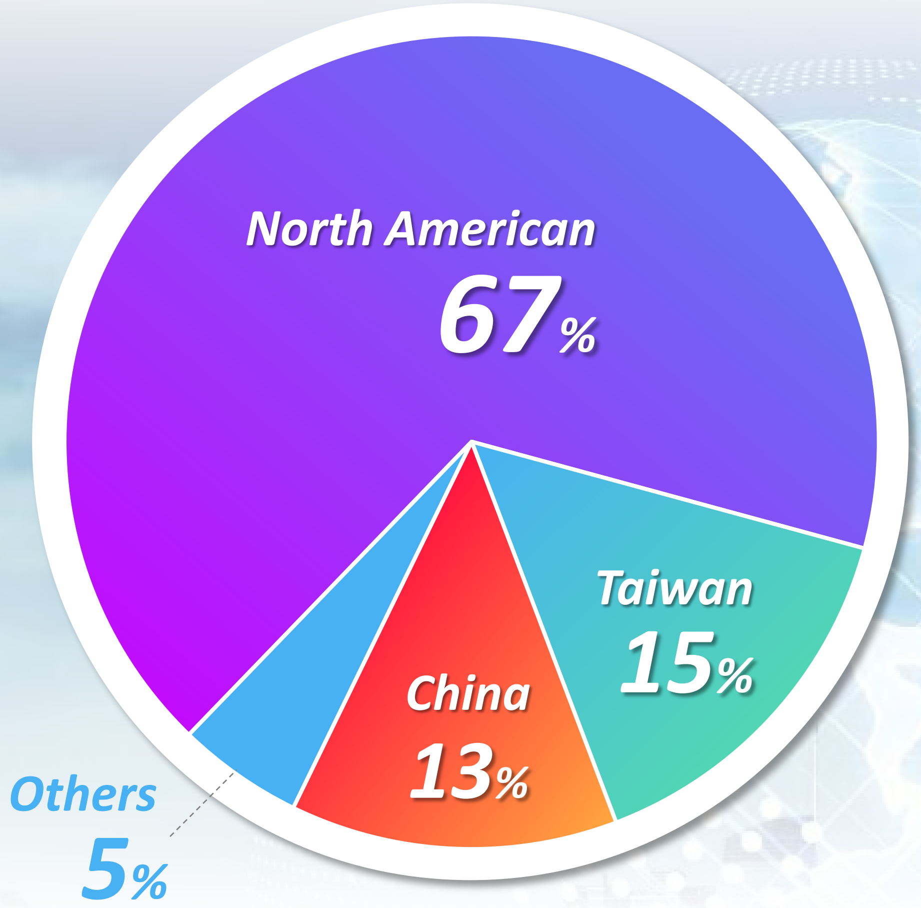
高速
老化測試
Functional Burn-in


Burn-in Socket

DFT Design For Testing
DFM Design For Manufacturing

全球客戶營收占比

First 10 Months of 2025



87% Top10 Customers

🟥 AI 🟥 ASIC 🟥 CPU
🟥 HPC 🟥 AP 🟥 GPU

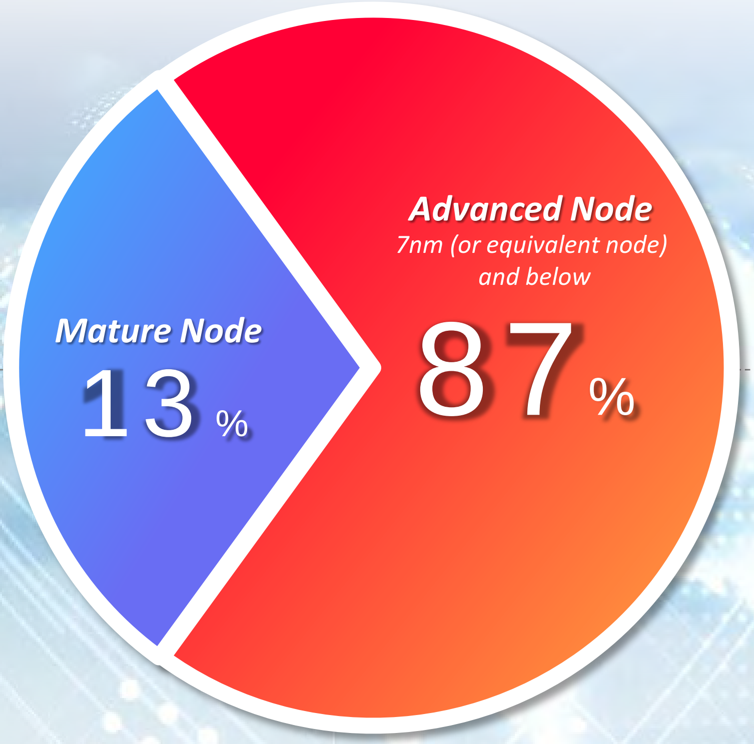
200^{+} Active Customers

🟦 IC Design 🟦 Foundry 🟦 OSAT
🟦 CSP 🟦 ASIC 🟦 IDM

WinWay
穎崴科技

客戶先進製程占比

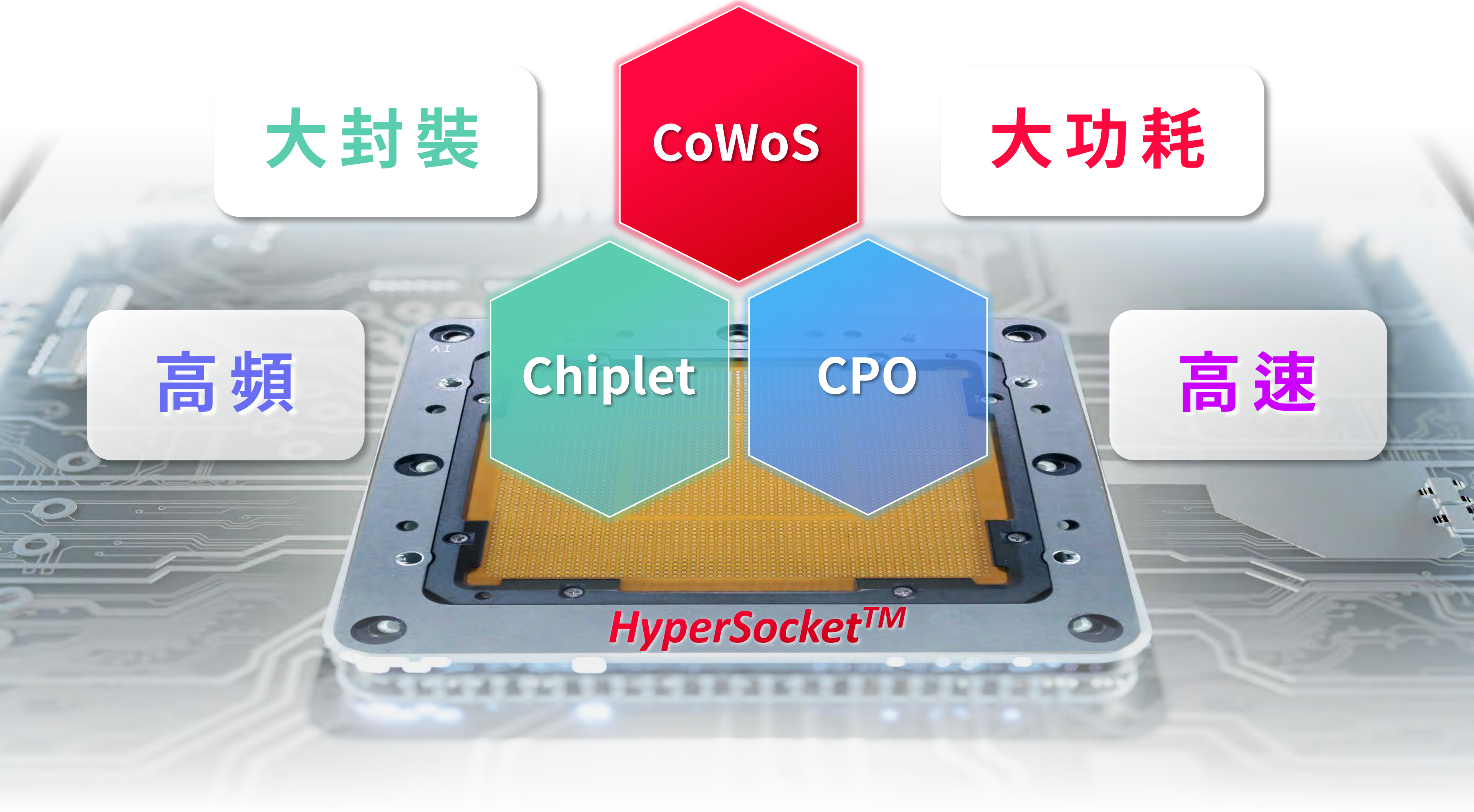
First 10 Months of 2025



- Automotive
- Networking
- IoT
- DTV & STB
- NAND Flash

- AI
- HPC
- GPU
- CPU
- Smart Phone

先進封裝推動高階測試需求



大封裝

大功耗

高頻

高速

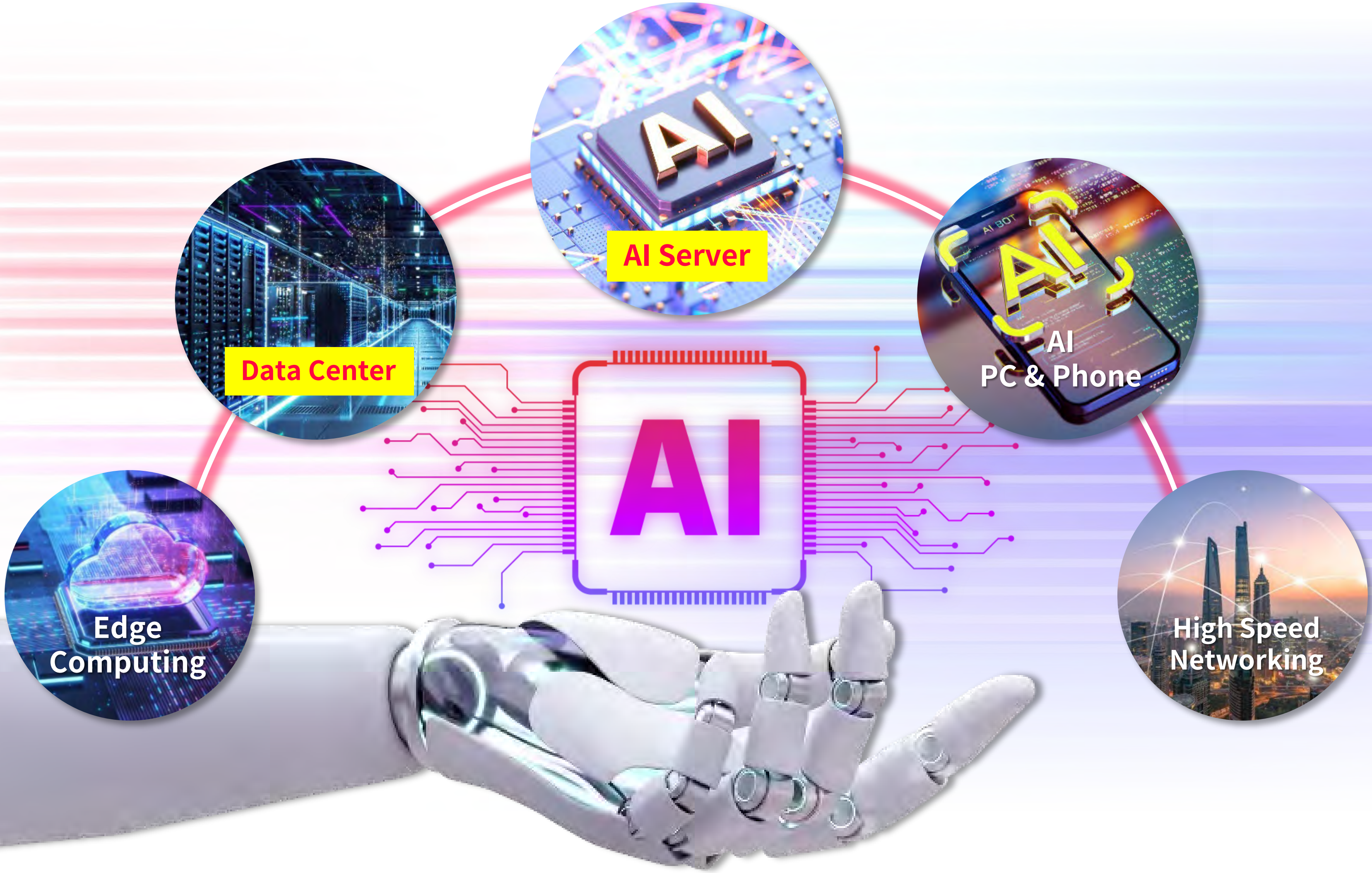
CoWoS

Chiplet

CPO

02 產業趨勢

半導體產業核心驅動力



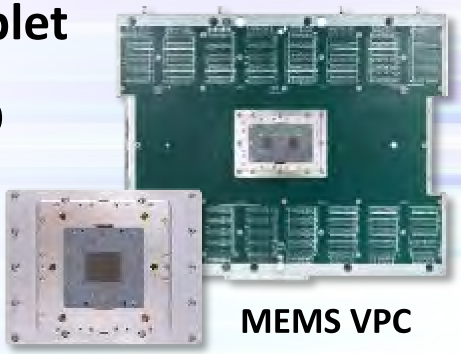
- Edge Computing
- Data Center
- AI Server
- AI PC & Phone
- High Speed Networking

晶圓測試重要性急速增加

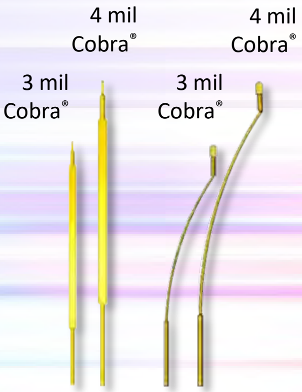
From the Shadows to the Spotlight

K.G.D Close to
Known **G**ood **D**ie

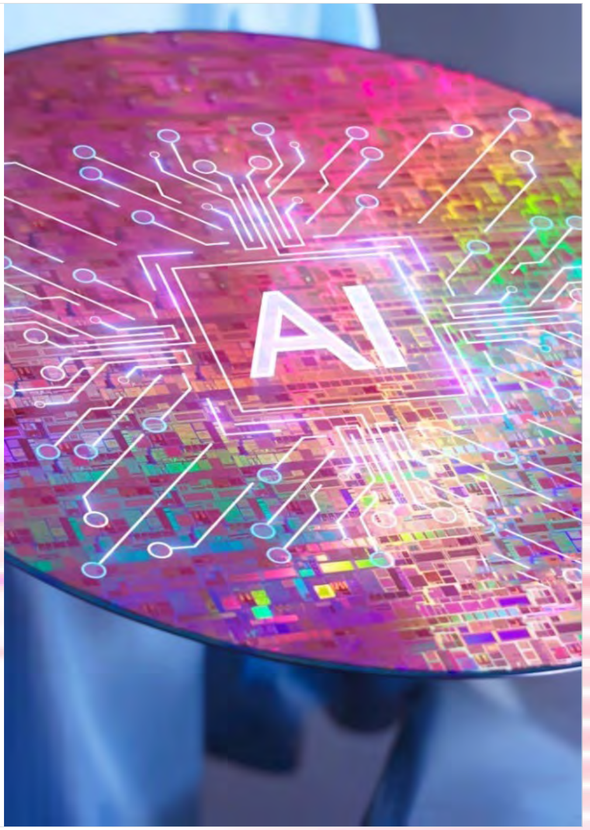
- **CoWoS**
- **Chiplet**
- **CPO**



MEMS VPC



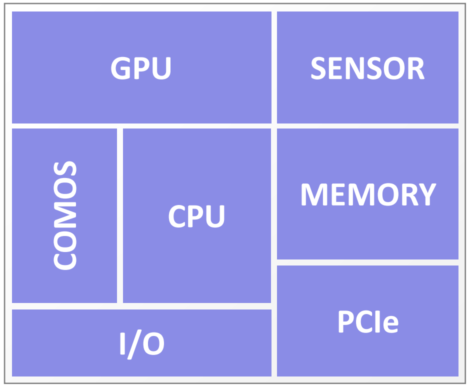
Cobra VPC



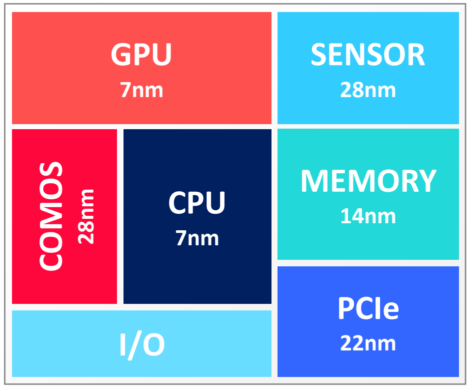
Known Good Die Is Required!

Probe Card Demand Induce

SoC One Probe Card



Chiplet Multiple Probe Card Demand

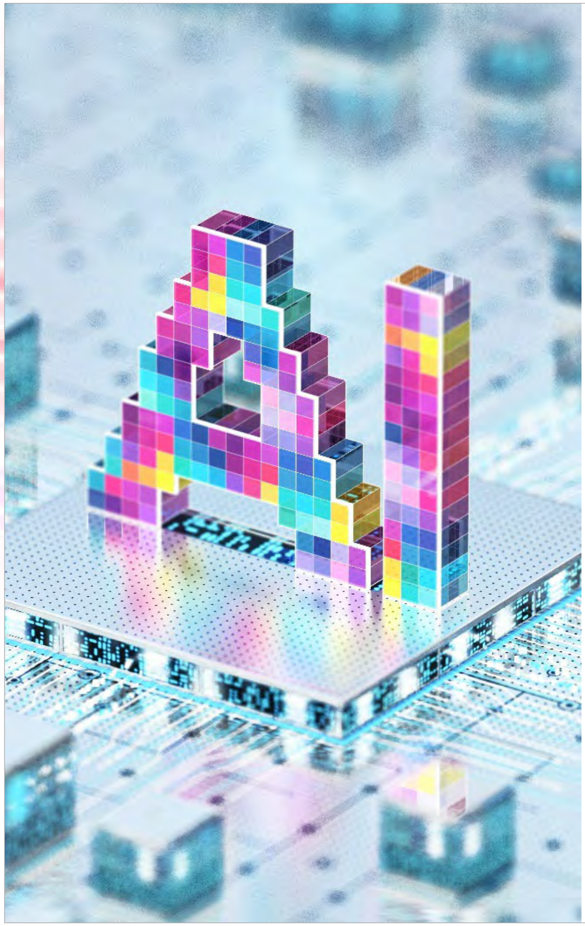


Source : Trend Force

Source: market.us

- Higher Pin Count
- Higher CCC
- Higher Speed
- Lower Force
- Smaller Pitch
- Wider Operation Temperature

AI 持續帶動系統測試高速成長



2026-2030 CAGR

SLT & SFT

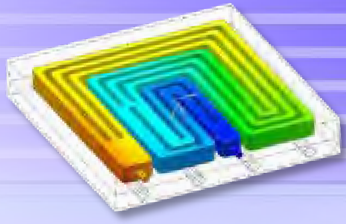
More than 15%

Greater than industry growth

Source: WinWay 2025

HyperSocket™

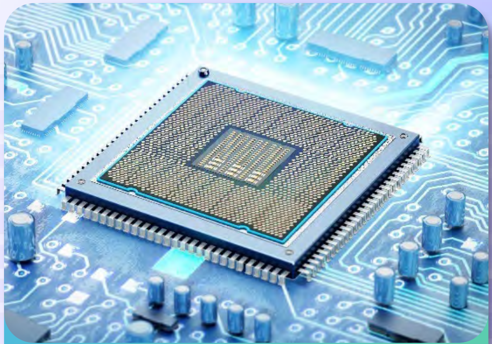
Coaxial Socket



(Liquid Cooling)

Thermal System

高速老化測試將成未來趨勢



Reliability Burn-in

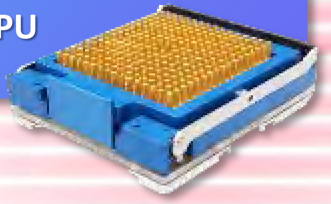
For all IC testing

Functional Burn-in

AI & HPC

Mass Production Burn-in

Automotive
CPU GPU

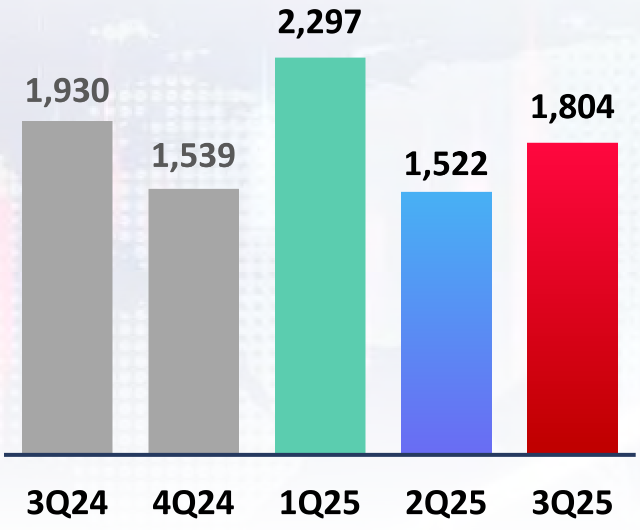


03 經營績效

營收持續成長

QUARTERLY REVENUE

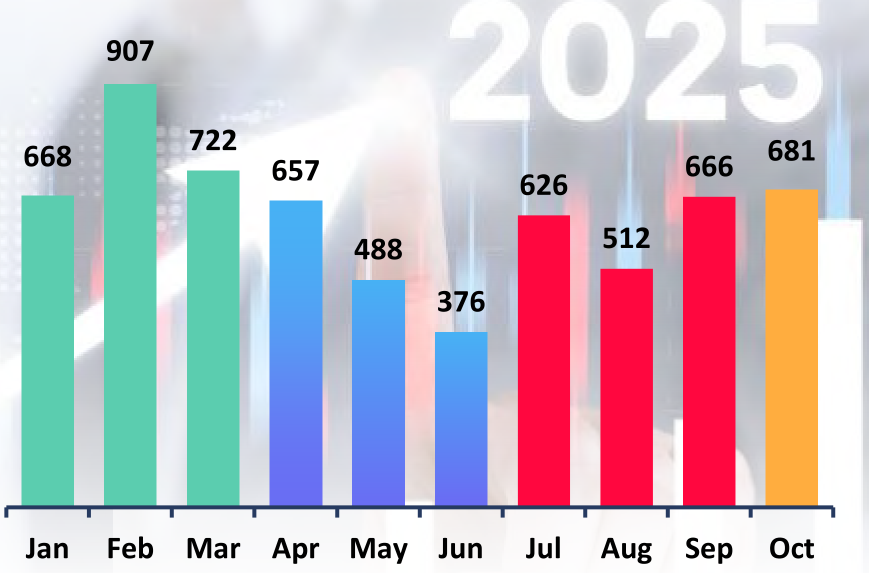
(NTD MILLION)



YoY	96%	129%	114%	21%	-7%
QoQ	54%	-20%	49%	-34%	19%

MONTHLY REVENUE

(NTD MILLION)

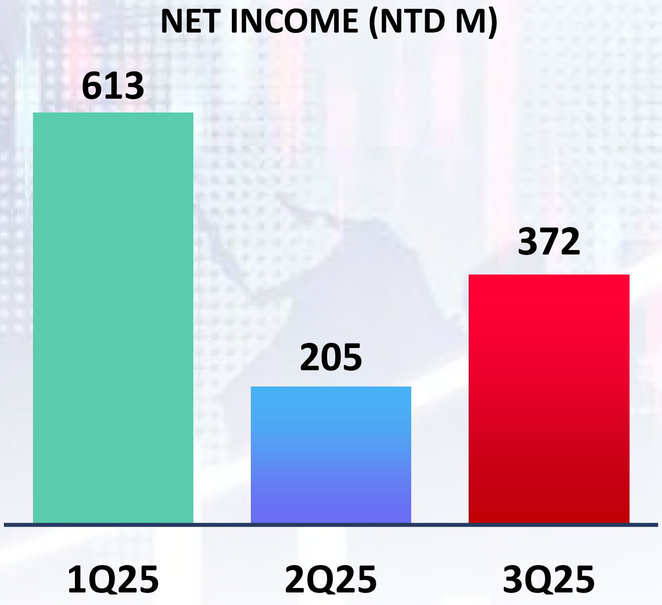


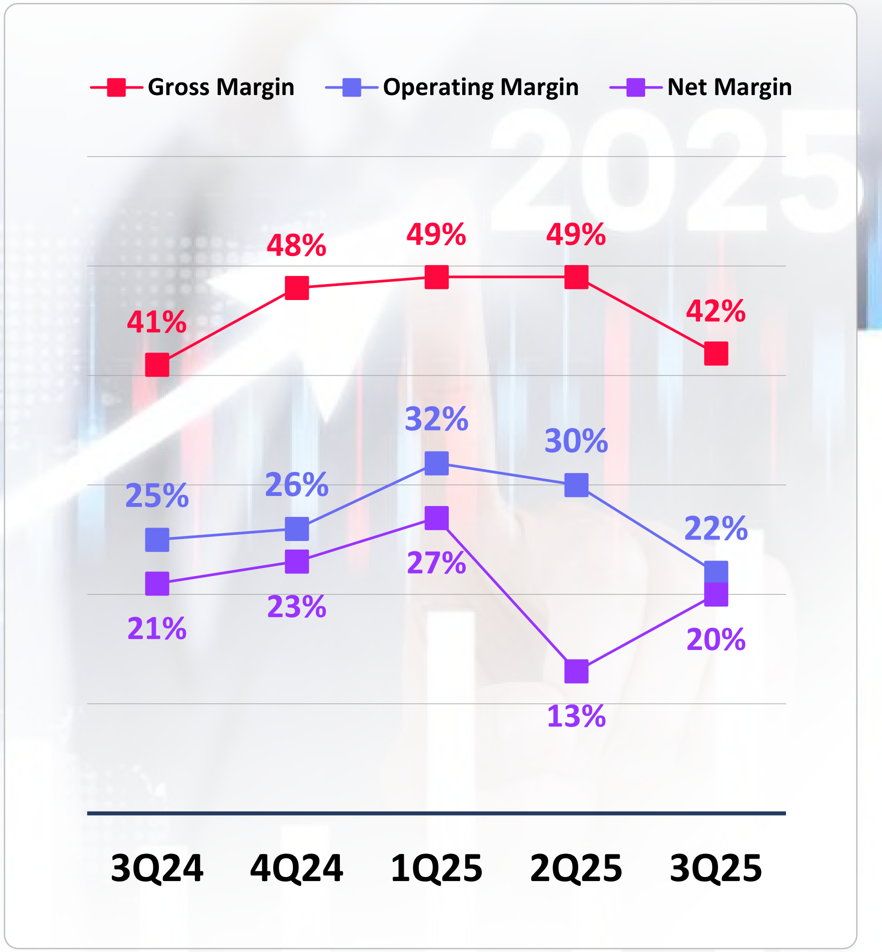
YoY	82%	191%	84%	40%	37%	-12%	5%	-18%	-6%	5%
MoM	47%	36%	-20%	-9%	-26%	-23%	66%	-18%	30%	2%

獲利再創新高

2025
Q1-Q3 EPS **33.4** (NT$)

EPS	17.21	5.76	10.43

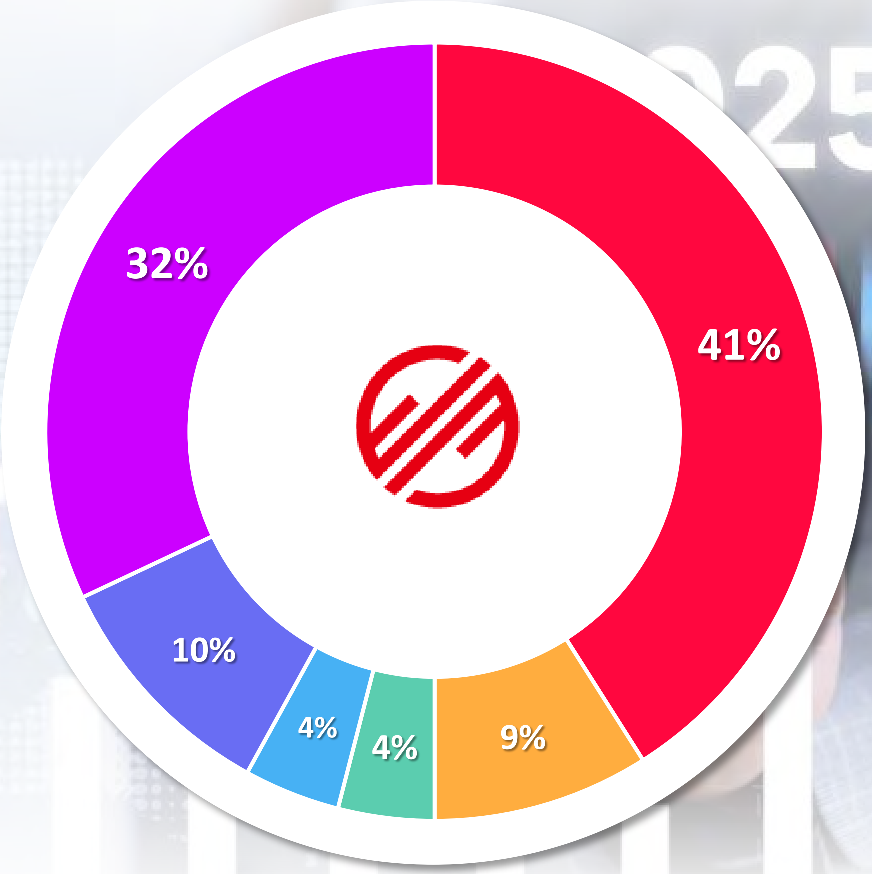




產品組合優化

First 10 Months of 2025

🟥	**Coaxial Socket**	**41 %**
🟪	**Probe Card**	**32 %**
🟦	**Contact Element**	**10 %**
🟧	**RF & Plastic Socket**	**9 %**
🟩	**Burn-in Socket**	**4 %**
🟦	**Others**	**4 %**

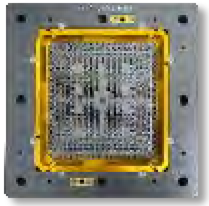


產品應用廣泛

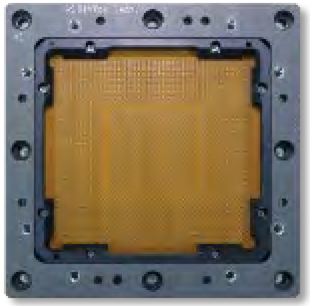
First 10 Months of 2025

HPC & AI

44 %



Coaxial Socket



HyperSocket™

PC & Gaming

31 %

POP Plastic Socket

Smart Phone

5 %

POP Plastic Socket

**Networking
Auto / Others**

20 %

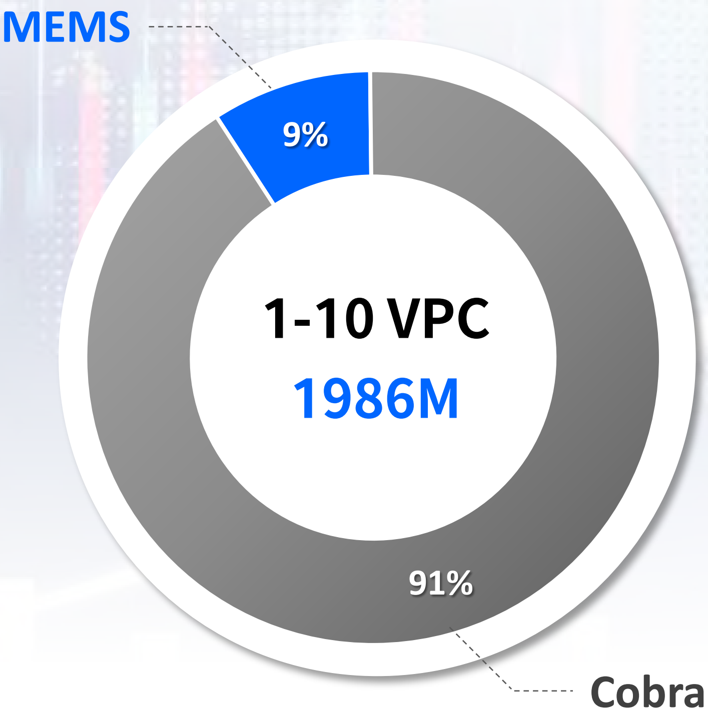
Plastic Socket

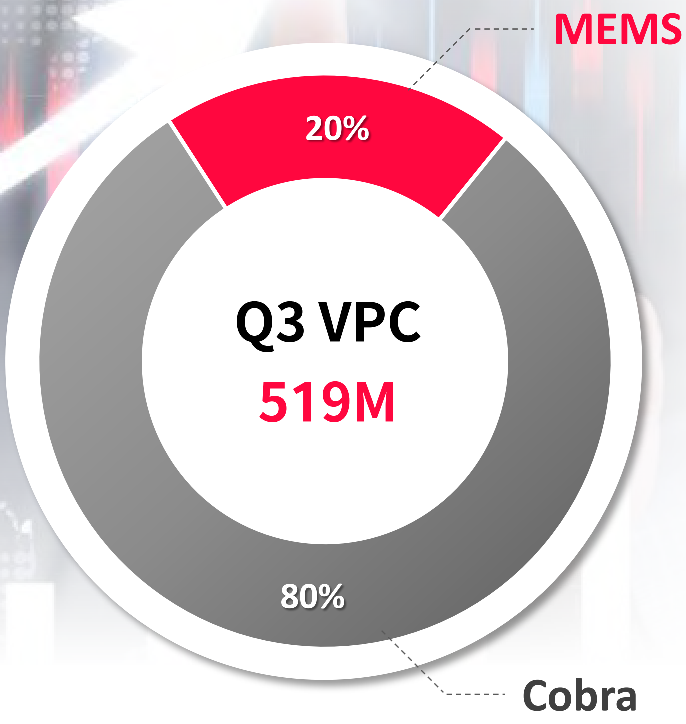
MEMS Probe Card 發酵

First 10 Months of 2025

1-10 MEMS VPC 9%

Q3 MEMS VPC 20%



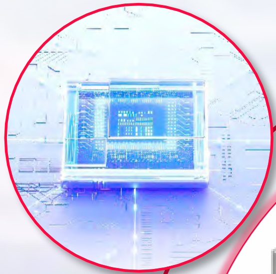


04 研發創新

革新高階半導體測試方案

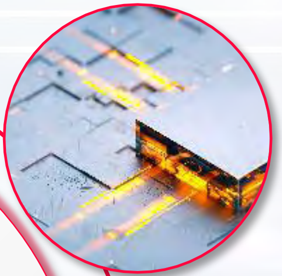
雙層超導測試座 HyperSocket™

大封裝



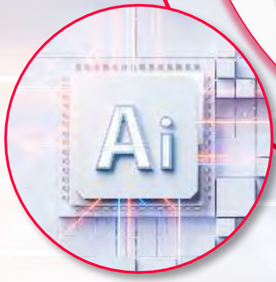
加大接觸面積
提升散熱效益
提高測試穩定性

高速率



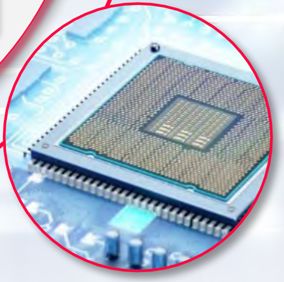
全金屬屏蔽，短迴路設計
滿足224Gbps以上測試需求

大功耗



平行電流路徑
大幅降低溫升

高腳數



零預壓創新設計
延長維護週期

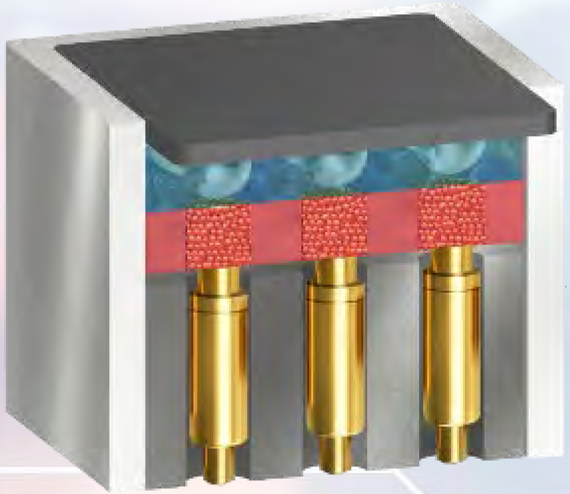
Patent NO. TWI862047 TWI884802 TWI862191 TWI901161 CN20570508U

Patent Pending USA Malaysia

WinWay
穎崴科技

革新高階半導體測試方案

高電流液冷方案 Liquid Cooling Socket

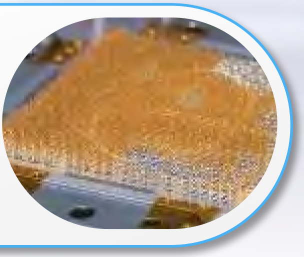


Patent NO. TWI901181

提升測試散熱效率

提高先進封裝測試穩定性

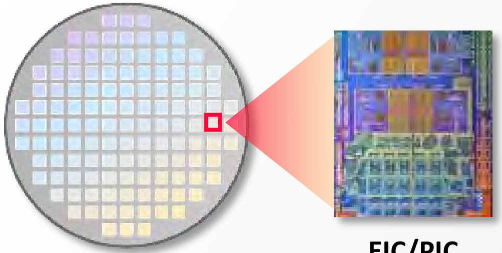
提高探針測試壽命



矽光子CPO 測試方案導入

CPO 全域性測試架構

Wafer Level → Die Level



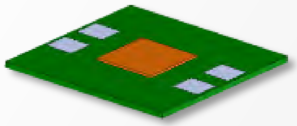
Silicon Photonic Wafer

EIC/PIC Die

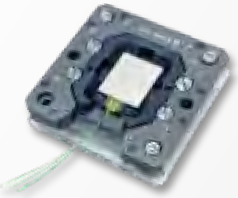
WLCSP Fine Pitch Socket
(PIC & EIC Wafer test)

Package Level

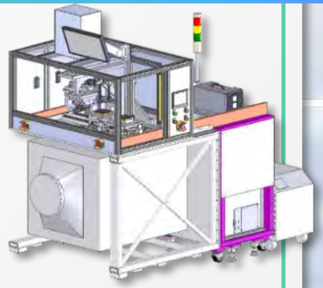
Optical Engine



CPO Substrate

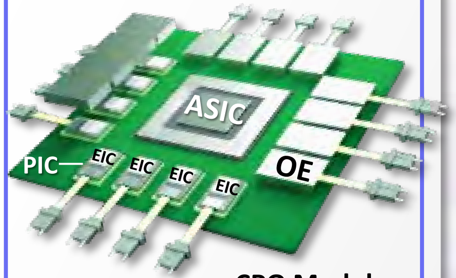


Optical and Electrical Test Socket
(Optical Engine)



Double Sided Probing System

Module Level



CPO Module
Source: ASE官網

Coaxial Socket

首推 3500W 超高功率溫控方案

E-Flux6.0 液冷溫控系統

AI 晶片帶動高功率散熱需求

2026 — ~2,000W

2030 — ~4,000W

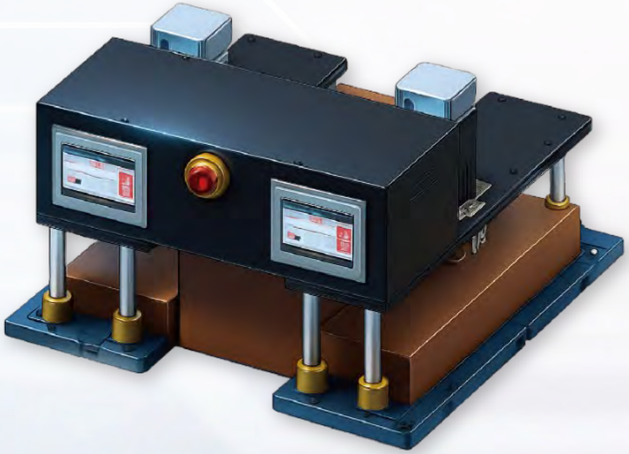
203x — ~6,000W

AI Server 板級測試方案

Rack level 檢測需求


AI Data Center


AI Server


SLT Plunger System

探針自製效益持續顯現

Socket All in House

成本優化

自製率提升，優化毛利結構

技術自主

掌握關鍵製程技術，優化探針特性

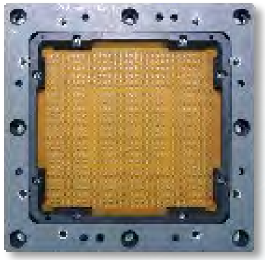
品質控管

產品品檢嚴謹，卓越客戶體驗

交期彈性

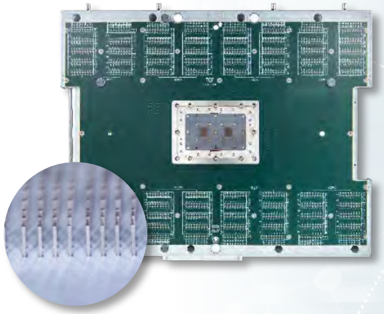
物料彈性調度，快速應變需求

明年營收成長驅動力



HyperSocket™

迎接AI高成長產品應用



MEMS Probe Card

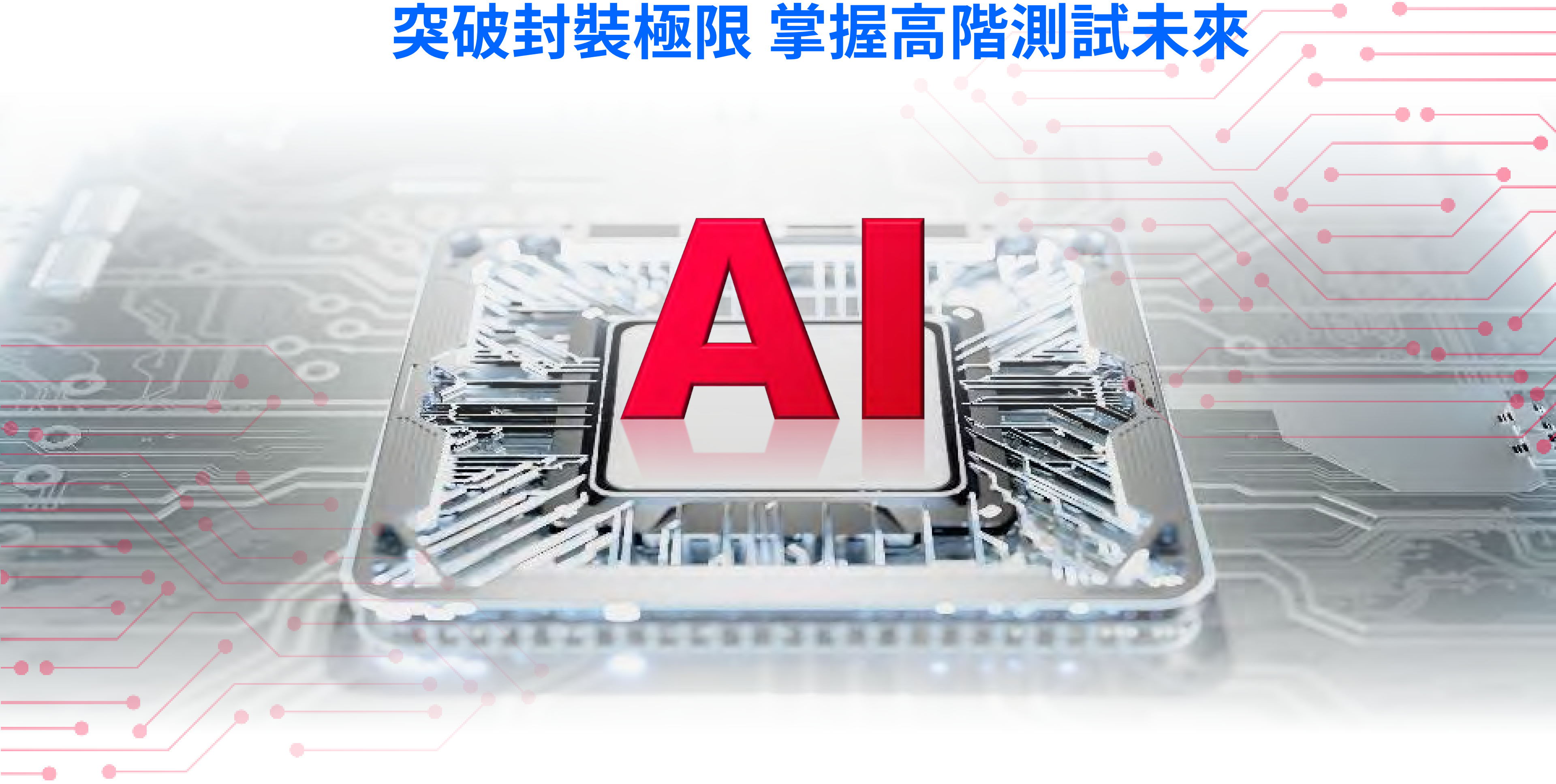
專注AI產品落實在地服務

Functional Burn-in

全球首創掌握市場先機

先進製程高階封測帶來的機會與挑戰

突破封裝極限 掌握高階測試未來

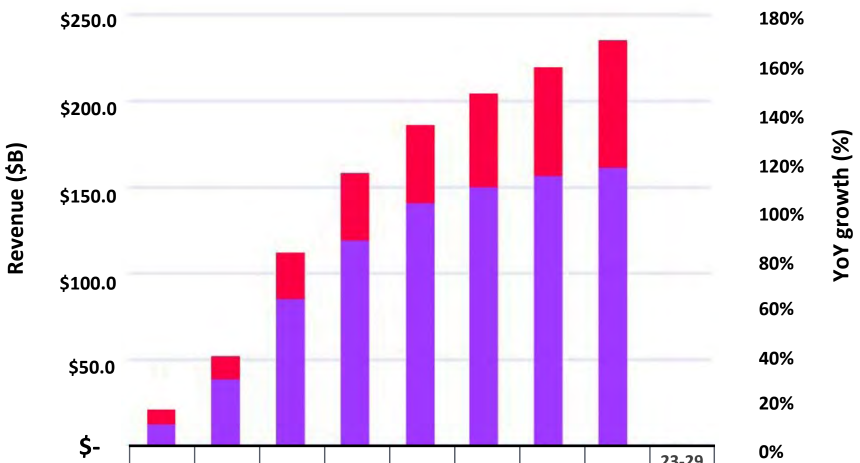


Advanced Package Application and Market Trend

Data Center AI Chip & ASIC

Datacenter GPU and AI ASIC revenue forecast

AI ASIC CAGR **35.0%** GPU CAGR **26.9%**



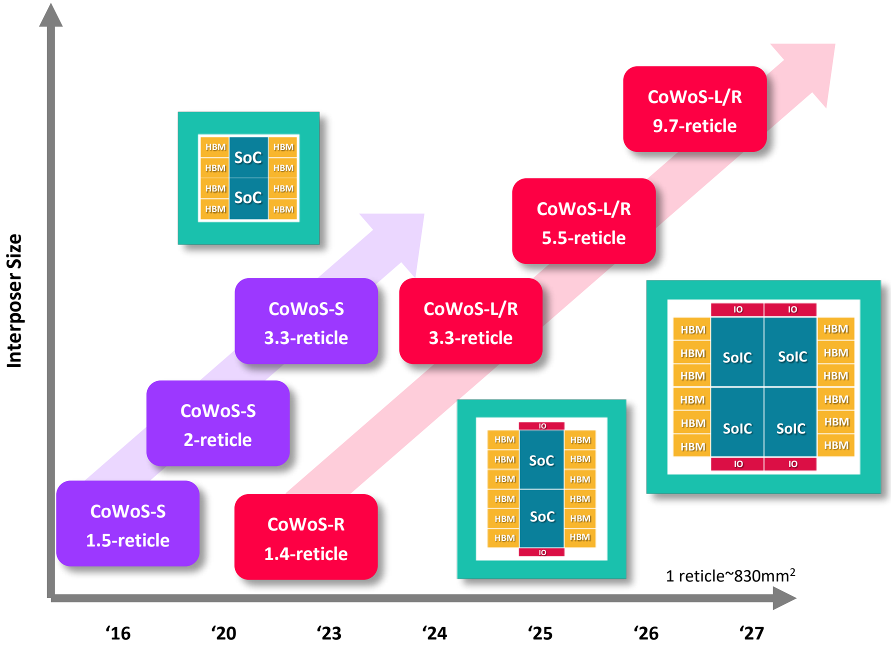
	2022	2023	2024	2025	2026	2027	2028	2029	23-29 CAGR
🟥 AI ASIC	$6.3	$11.8	$25.3	$36.8	$45.1	$52.5	$61.1	$71.1	35.0%
🟪 GPU	$12.6	$38.8	$85.6	$119	$139	$150	$157	$162	26.9%
Total	$18.9	$50.5	$110	$156	$185	$202	$218	$233	29.0%
YoY(%)	38%	167%	120%	41%	19%	10%	8%	7%	

Source: Yole

WinWay 穎崴科技

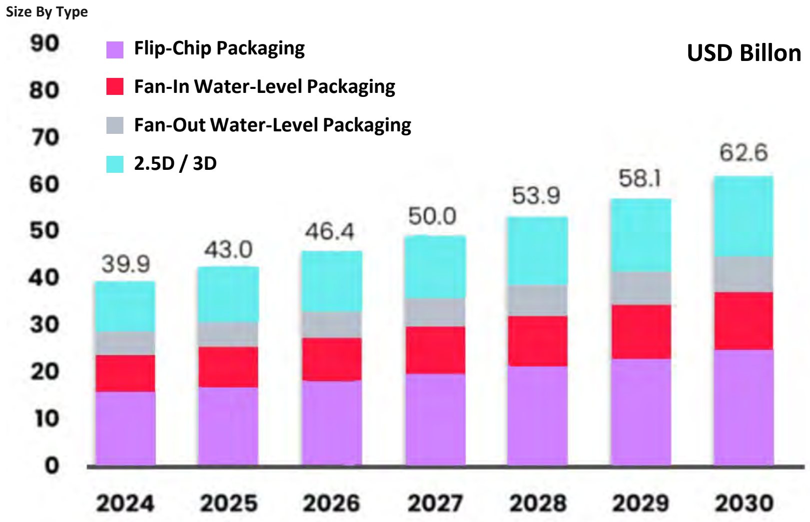
Advanced Package Application and Market Trend

CoWoS Enables AI Compute Scaling



Source: TSMC

Global Advanced Semiconductor Packaging Market



The Forecasted Market Size for 2030 is USD $62.6B

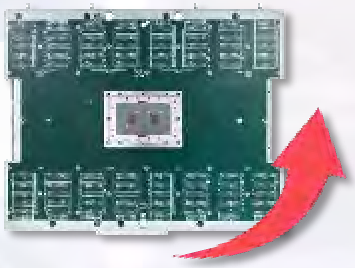
The Market will Grow At the CAGR of 7.8%

Source: market.us

測試時間大幅增長

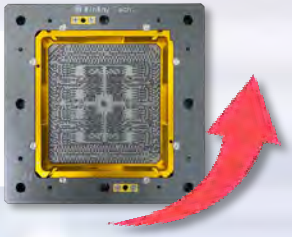
Longer Wafer Sort Test Time

MEMS and Cobra Probe card



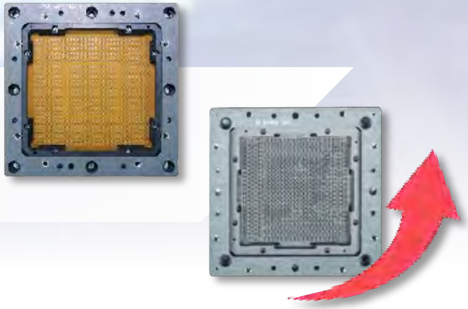
Longer FT (ATE) Test Time

Plastic, Coaxial and HyperSocket™



Longer SLT Test Time

Coaxial and HyperSocket™



測試項目增加

More Reliability Test Insertion

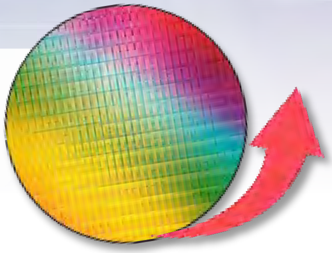
Functional Burn-In Socket

Bigger and Bigger Device Package
Higher and Higher Device Power Consumption

HyperSocket™ and HyperSocket™ -DF

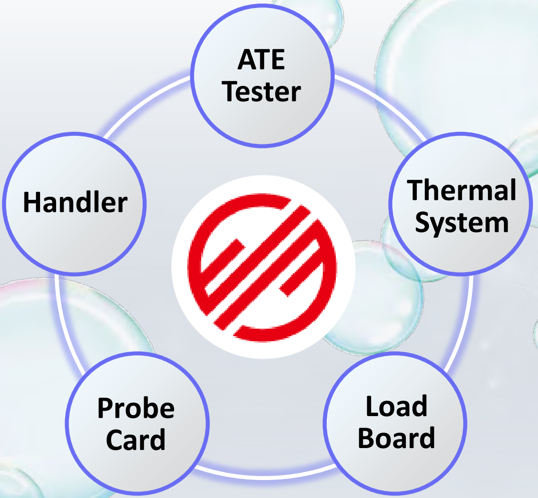
Longer and Longer Fab In-process Time

Fab and OSAT expansion drive equipment demand



半導體產業異質整合

Alliance **I**ntegration **H**eterogeneous



ATE Tester

Thermal System

Load Board

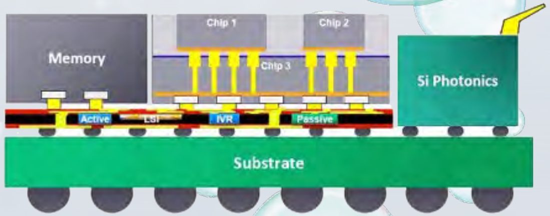
Probe Card

Handler

AI

Artificial Intelligence

CPU、GPU、HPC



Source: TSMC

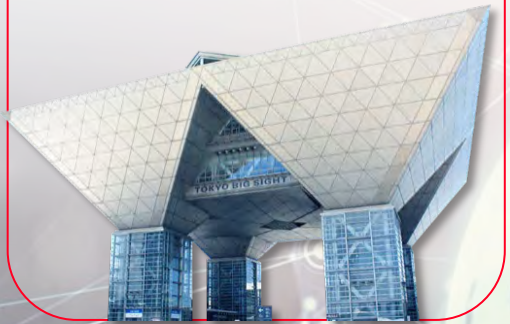
HI

SEMICON JAPAN

2025.12.17—19

Japan

Tokyo Big Sight, Tokyo

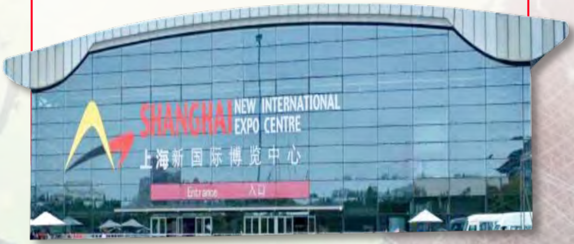


SEMICON China

2026.03.25—27

China

Shanghai New International Expo Centre



SEMICON SEA

2026.05.05—07

Malaysia

Malaysia International Trade & Exhibition Centre

Q&A

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THANK YOU

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